

J243-VB Datasheet P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)	Q _g (TYP.) (nC)			
	0.450 at V _{GS} = -10 V	-0.40				
-20	0.500 at V _{GS} = -4.5 V	-0.36	1			
	0.600 at V _{GS} = -2.5 V	-0.32				

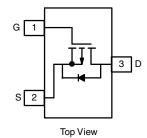
FEATURES

- Trench power MOSFET
- 100 % R tested
- Fast switching speed



APPLICATIONS

- Load / power switch for portable devices
- Drivers: relays, solenoids, displays
- Battery operated systems



ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V _{DS}	-20	V	
Gate-Source Voltage		V _{GS}	± 20	V	
Opation	T _A = 25 °C		-0.40 b, c		
Continuous Drain Current (T _J = 150 °C)	T _A = 70 °C	I _D	-0.31 ^{b, c}	٦ ,	
Pulsed Drain Current (t = 300 μs)		I _{DM}	-1.6	A	
Continuous Source-Drain Diode Current	T _A = 25 °C	Is	-0.16 ^{b, c}		
Mayimum Dayar Dissination	T _A = 25 °C	Б	0.19 ^{b, c}	10/	
Maximum Power Dissipation	T _A = 70 °C	P _D	0.12 ^{b, c}	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +150	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum Junction-to-Ambient ^{a, b}	t ≤ 5 s	R_{thJA}	440	530	°C/W	
iviaximum sunction-to-ambient 4, 2	Steady State		540	650		

Notes

- a. Maximum under steady state conditions is 650 $^{\circ}\text{C/W}.$
- b. Surface mounted on 1" x 1" FR4 board.
- $c. \ t=5 \ s.$

服务热线:400-655-8788

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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static	STWIBOL	TEST CONDITIONS	IVIIIV.	116.	WAX.	ONT	
Drain-Source Breakdown Voltage	V_{DS}	V _{GS} = 0, I _D = -250 μA	-20		_	V	
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	VGS = 0, ID = 200 μΛ	-	-12	_	+ · ·	
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J	—— In = -250 uA		1.8	_	mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 0.6	-	-1.5	V	
date-source Theshold Voltage	I _{GSS}	$V_{DS} = V_{GS}, V_{DS} = \pm 8 \text{ V}$	- 0.0	_	± 30	+	
Gate-Source Leakage		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$	-	-	± 1	μΑ	
		$V_{DS} = -20 \text{ V}, V_{GS} = 14.3 \text{ V}$ $V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	<u>- '</u> -1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -20 V, V _{GS} = 0 V, T _J = 85 °C	_	_	-10	_	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, 13 = 65 \text{ C}$ $V_{DS} = 25 \text{ V}, V_{GS} = -4.5 \text{ V}$	-1.5	_	-	Α	
On State Brain Surrent	iD(on)	$V_{GS} = -10 \text{ V}, V_{GS} = -0.4 \text{ A}$	-	0.450	_		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -0.2 \text{ A}$	- 0.450 -		Ω		
Drain Godice on Gtate nesistance	TiDS(on)	$V_{GS} = -2.5 \text{ V}, I_D = -0.1 \text{ A}$	_	0.600	_	- 12	
Forward Transconductance	9 _{fs}	V _{DS} = -10 V, I _D = 0.4 A	_	1	_	S	
Dynamic b	gis	VDS = 10 V, ID = 0.471		'			
Input Capacitance	C _{iss}		_	45	_		
Output Capacitance	Coss	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	_	15	_	pF	
Reverse Transfer Capacitance	C _{rss}	753	_	10	_		
		V _{DS} = -10 V, V _{GS} = -4.5 V, I _D = -0.4 A	-	1.65			
Total Gate Charge	Q_g		-	1	2	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = -0 \text{ V}, V_{GS} = -2.5 \text{ V}, I_{D} = -0.4$	-	0.2	-		
Gate-Drain Charge	Q _{gd}	, 45 , 5	-	0.26	-		
Gate Resistance	R _g	f = 1 MHz	2.4	12	24	Ω	
Turn-On Delay Time	t _{d(on)}		-	9	18		
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_L = 33.3 \Omega$	_	10	20		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -0.3 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$	_	10	20	1	
Fall Time	t _f		-	8	16		
Turn-On Delay Time	t _{d(on)}		-	1	2	ns	
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_L = 33.3 \Omega$	-	8	16		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -0.3$ A, $V_{GEN} = -8$ V, $R_g = 1$ Ω	-	9	18		
Fall Time	t _f		-	5	10		
Drain-Source Body Diode Characteris	tics		1			l.	
Pulse Diode Forward Current ^a	I _{SM}		-	-	-1.5	А	
Body Diode Voltage	V _{SD}	I _S = -0.3 A	-	-0.8	-1.2	V	
Body Diode Reverse Recovery Time	t _{rr}		-	16	24	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 004 41/11 4024/	-	8	16	nC	
Reverse Recovery Fall Time	ta	$I_F = -0.3 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$	-	11	-		
Reverse Recovery Rise Time	t _b		_	5	-	ns	

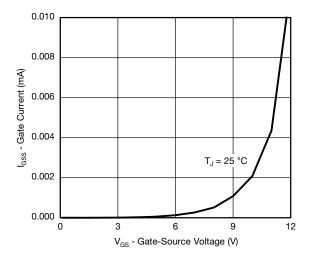
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

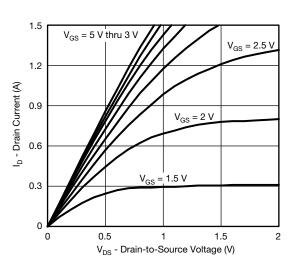
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



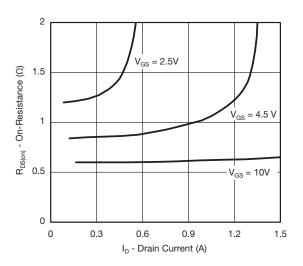
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



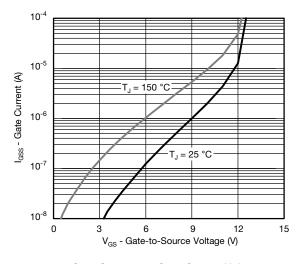
Gate Current vs. Gate-Source Voltage



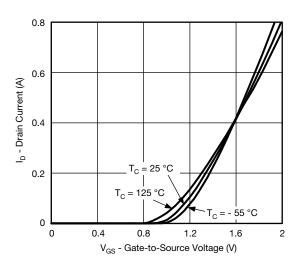
Output Characteristics



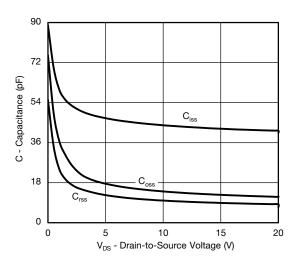
On-Resistance vs. Drain Current



Gate Current vs. Gate-Source Voltage



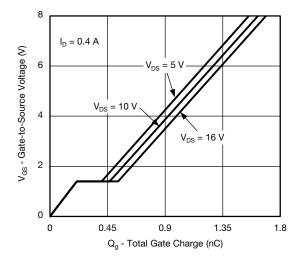
Transfer Characteristics



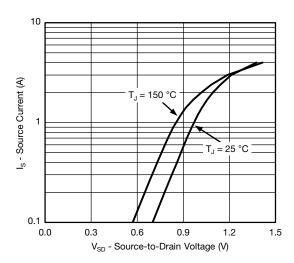
Capacitance



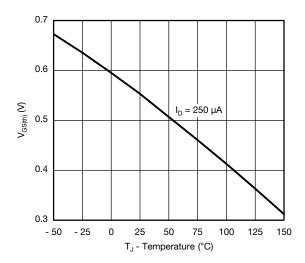
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



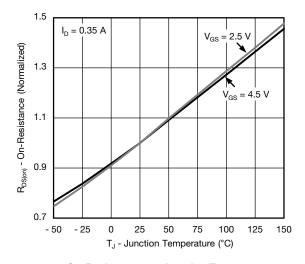
Gate Charge



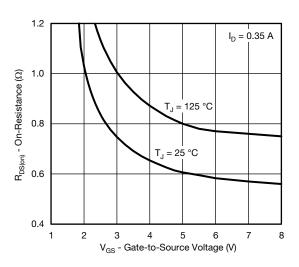
Source-Drain Diode Forward Voltage



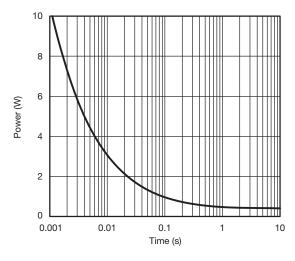
Threshold Voltage



On-Resistance vs. Junction Temperature



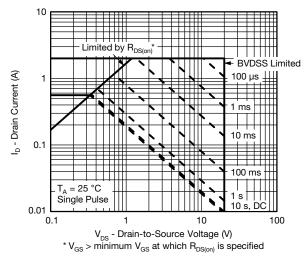
On-Resistance vs. Gate-to-Source Voltage

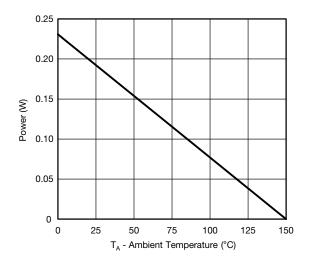


Single Pulse Power, Junction-to-Ambient



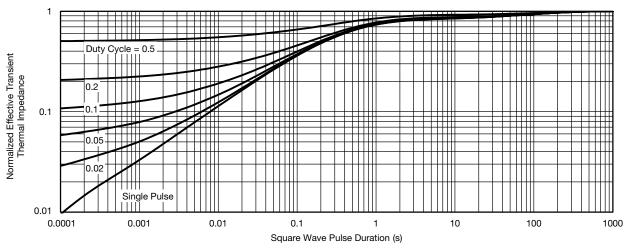
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Safe Operating Area, Junction-to-Ambient

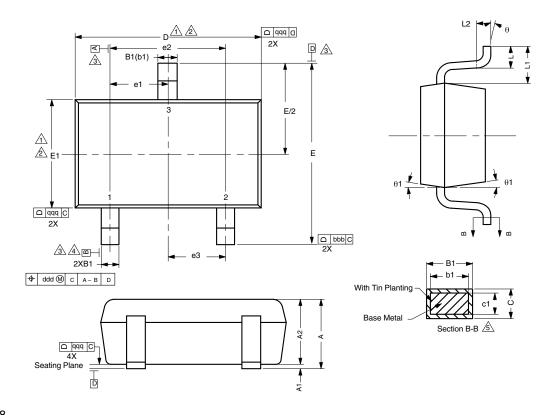
Power Derating, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient



SC-75A: 3 Leads



DWG: 5868

Notes

 $\underset{\wedge}{\text{Dimensions in millimeters will govern.}}$

- Dimension D does not include mold flash, protrusions or gate burrs. Mold flash protrusions or gate burrs shall not exceed 0.10 mm per end. Dimension E1 does not include Interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.10 mm per side.
- Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, tie bar burrs, gate burrs and interlead flash, but including any mismatch between the top and bottom of the plastic body.
- ADatums A, B and D to be determined 0.10 mm from the lead tip.
- A Terminal positions are shown for reference only.

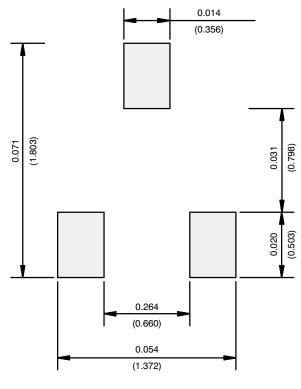
 These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

DIMENSIONS	TOLERANCES		
aaa	0.10		
bbb	0.10		
ccc	0.10		
ddd	0.10		

5114	N			
DIM.	MIN.	NOM.	MAX.	NOTE
Α	-	-	0.80	
A1	0.00	-	0.10	
A2	0.65	0.70	0.80	
B1	0.19	-	0.24	5
b1	0.17	-	0.21	
С	0.13	-	0.15	5
c1	0.10	-	0.12	5
D	1.48	1.575	1.68	1, 2
E	1.50	1.60	1.70	
E1	0.66	0.76	0.86	1, 2
e1	0.50 BSC			
e2	1.00 BSC			
e3	0.50 BSC			
L	0.15	0.205	0.30	
L1	0.40 ref.			
L2	0.15 BSC			
q	0°	-	8°	
q1	4°	-	10°	



RECOMMENDED MINIMUM PADS FOR SC-75A: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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